



US00D812241S

(12) **United States Design Patent** (10) **Patent No.:** **US D812,241 S**  
**LiCalzi et al.** (45) **Date of Patent:** **\*\* Mar. 6, 2018**

(54) **INSTRUMENT MODULE**

D685,483 S \* 7/2013 LiCalzi ..... D24/216  
D735,878 S \* 8/2015 Chang ..... D24/216  
D738,243 S \* 9/2015 Selberg ..... D10/81  
D740,955 S 10/2015 Gutmann et al.

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**FOREIGN PATENT DOCUMENTS**

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JP 1517913 S 2/2015  
WO DM081998 4/2014

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\* cited by examiner

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(\*\*) Term: **15 Years**

(57) **CLAIM**

(21) Appl. No.: **29/569,389**

The ornamental design for an instrument module, as shown  
and described.

(22) Filed: **Jun. 27, 2016**

**DESCRIPTION**

(51) **LOC (11) Cl.** ..... **24-01**

(52) **U.S. Cl.**  
USPC ..... **D24/216**

(58) **Field of Classification Search**  
USPC ..... D24/216, 111, 127, 107, 169, 186, 217,  
D24/219, 223–224, 231–234; D10/46,  
D10/70, 81, 97; 422/1, 62–65, 67, 68.1,  
422/70, 81, 129, 500, 506, 561,  
422/FOR. 106; 435/287.1, 287.3;  
436/43, 45, 47; 600/300, 301, 368, 372,  
600/481, 529, 544, 554, 561; 607/4, 5, 9,  
607/30

CPC ... G01R 31/31907; B04B 13/00; B04B 15/00;  
B04B 2005/0435; B04B 5/0421; A61B  
5/157; G06F 19/366; B01D 21/262

See application file for complete search history.

FIG. 1 is a front perspective view of an instrument module  
in accordance with an embodiment;  
FIG. 2 is a rear perspective view of an instrument module in  
accordance with an embodiment;  
FIG. 3 is a front elevational view of an instrument module  
in accordance with an embodiment;  
FIG. 4 is a rear elevational view of an instrument module in  
accordance with an embodiment;  
FIG. 5 is a left side elevational view of an instrument module  
in accordance with an embodiment;  
FIG. 6 is a right side elevational view of an instrument  
module in accordance with an embodiment;  
FIG. 7 is a top view of an instrument module in accordance  
with an embodiment; and,  
FIG. 8 is a bottom view of an instrument module in  
accordance with an embodiment.

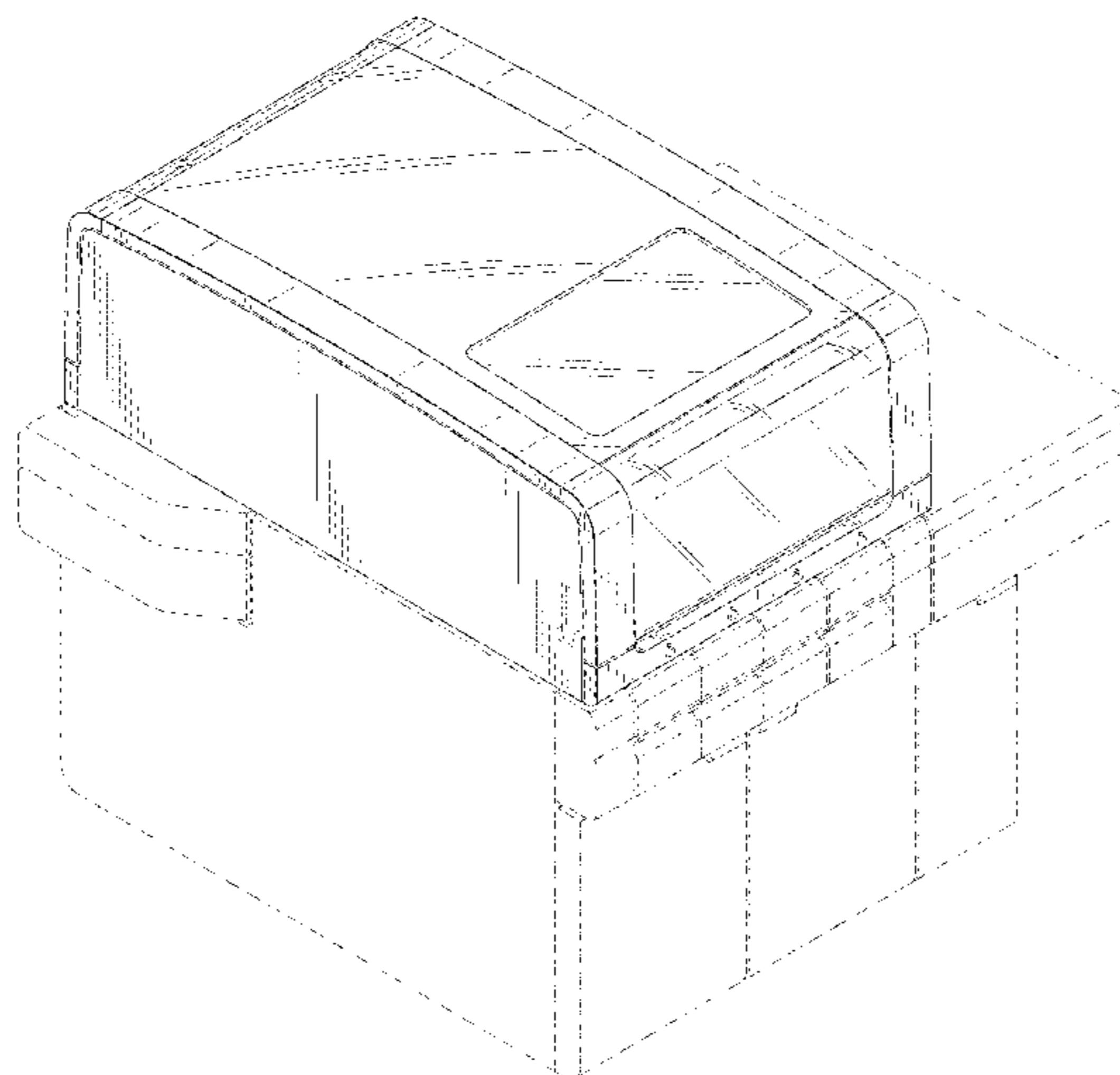
The broken lines shown in the figures represent portions of  
the instrument module that form no part of the claimed  
design. The broken line showing immediately adjacent the  
shaded areas represents boundaries to the claimed design  
and forms no part of the claimed design.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

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**1 Claim, 8 Drawing Sheets**



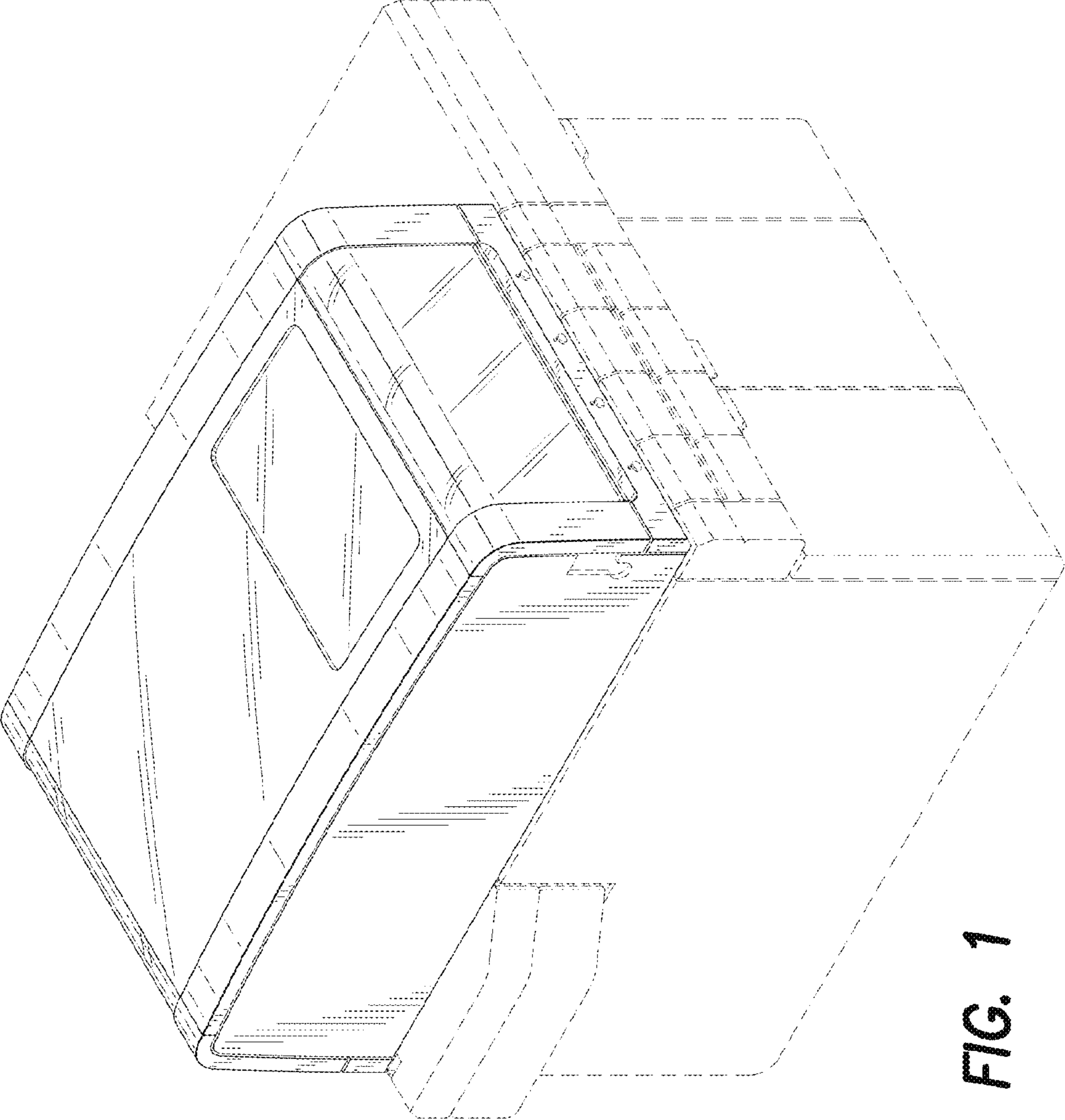


FIG. 1

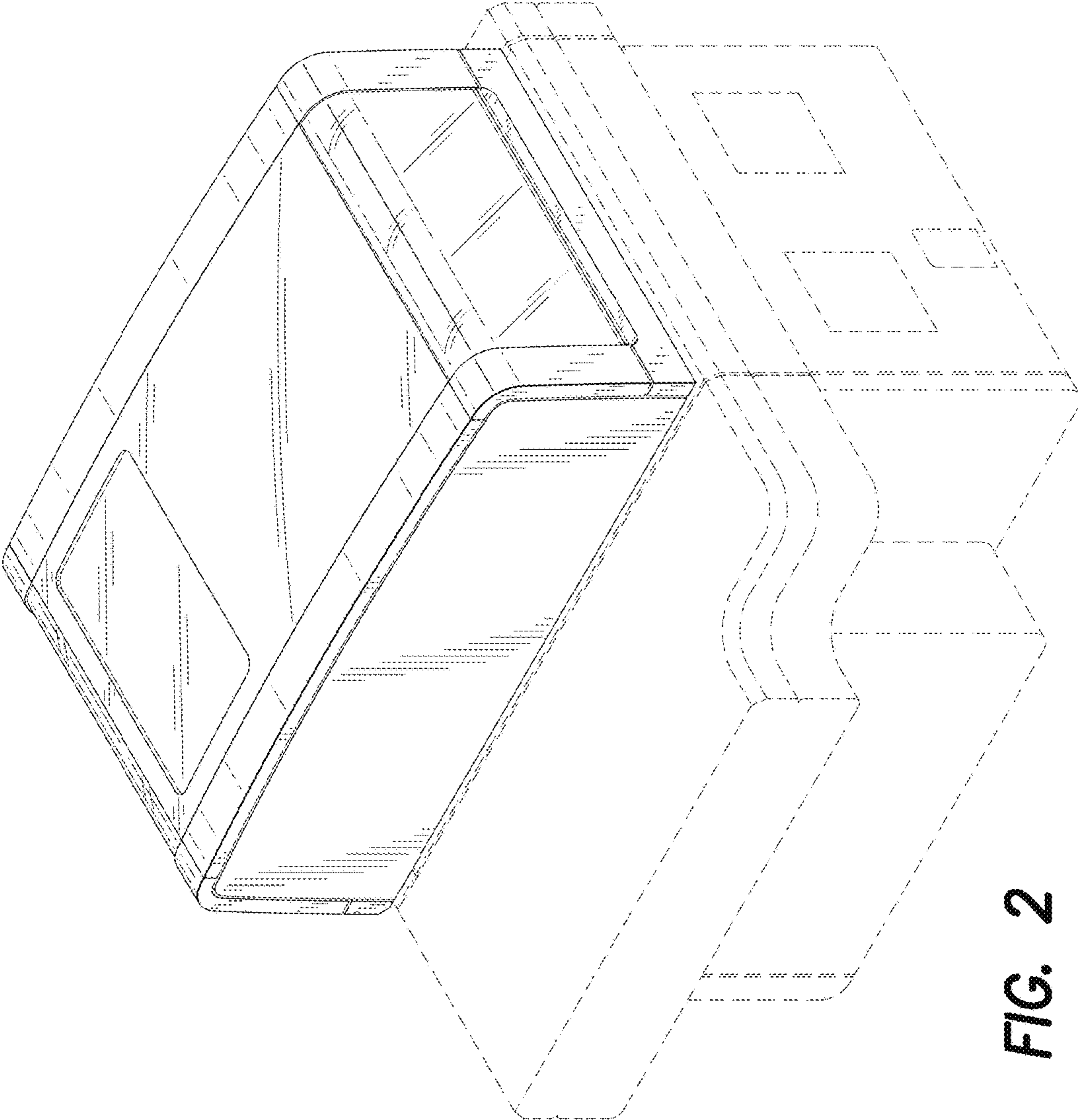


FIG. 2

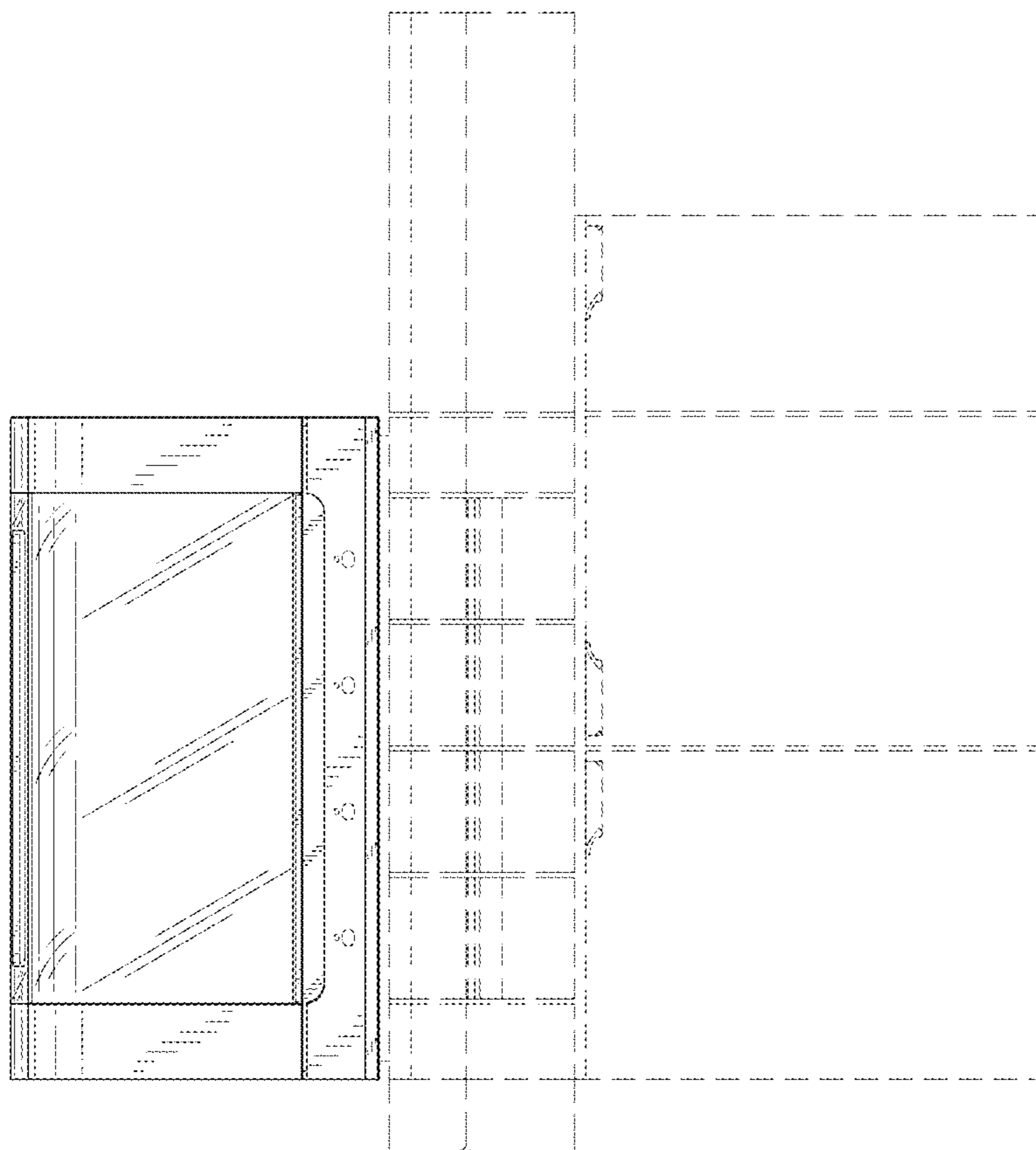
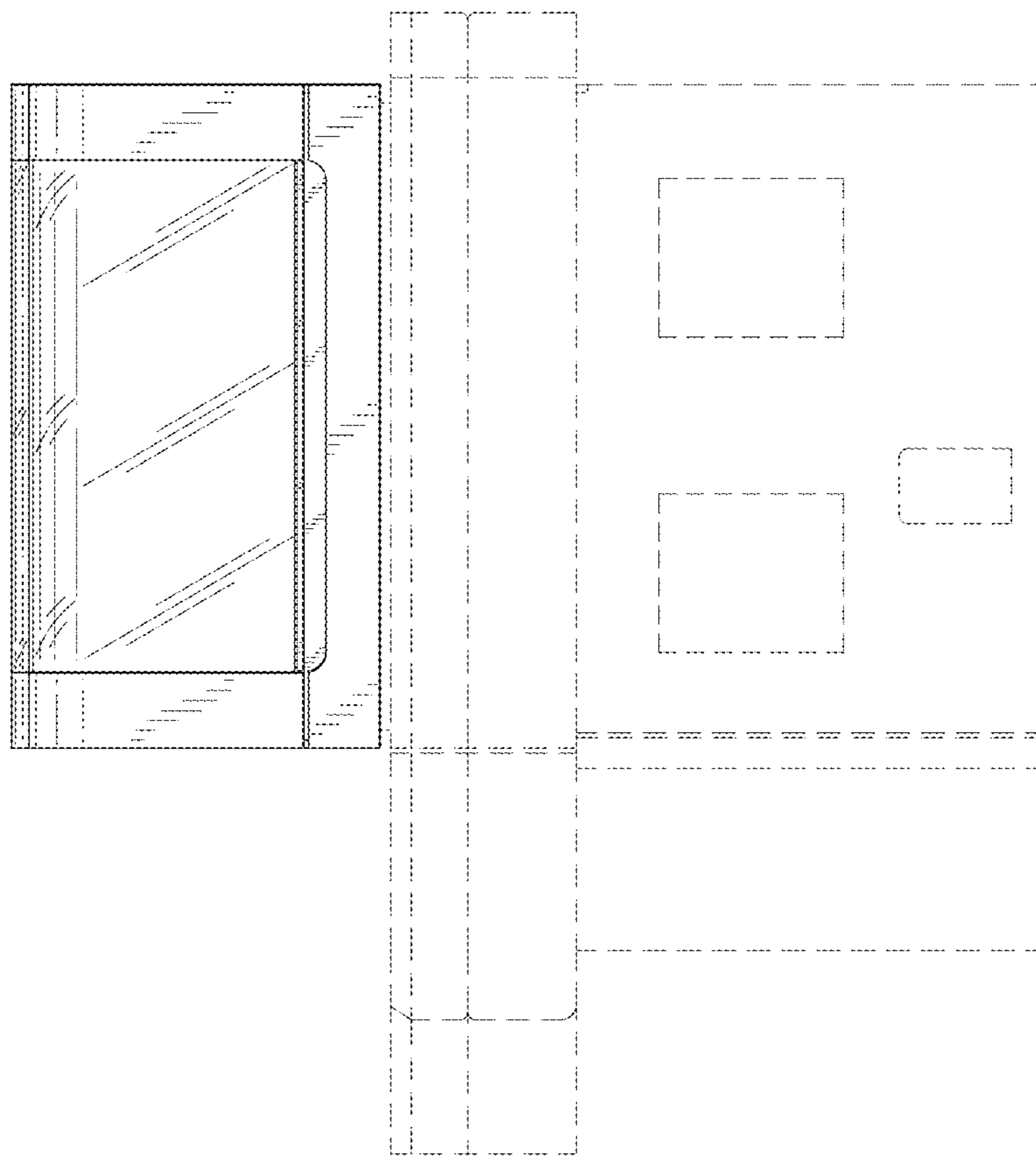


FIG. 3



**FIG. 4**

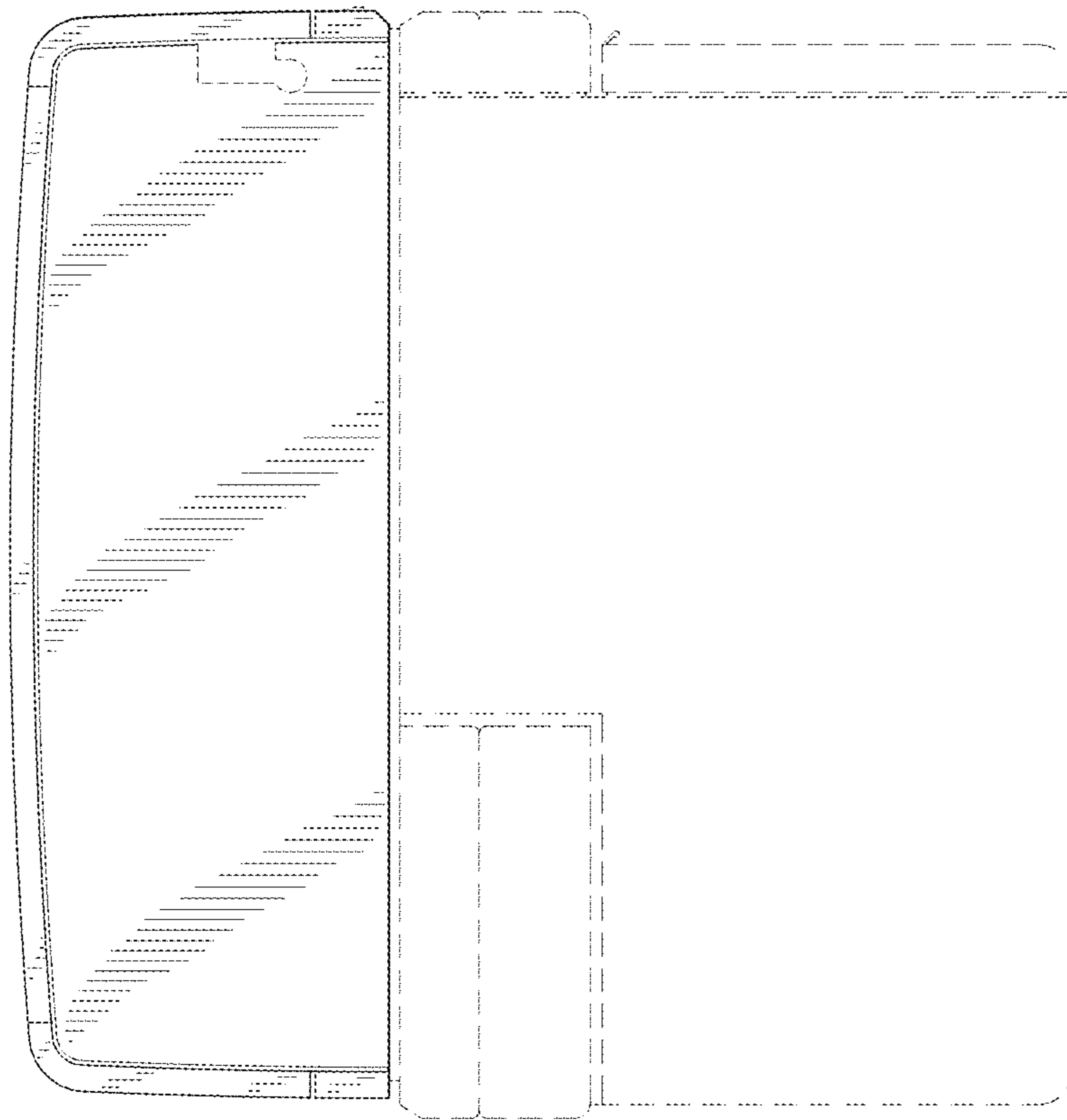


FIG. 5

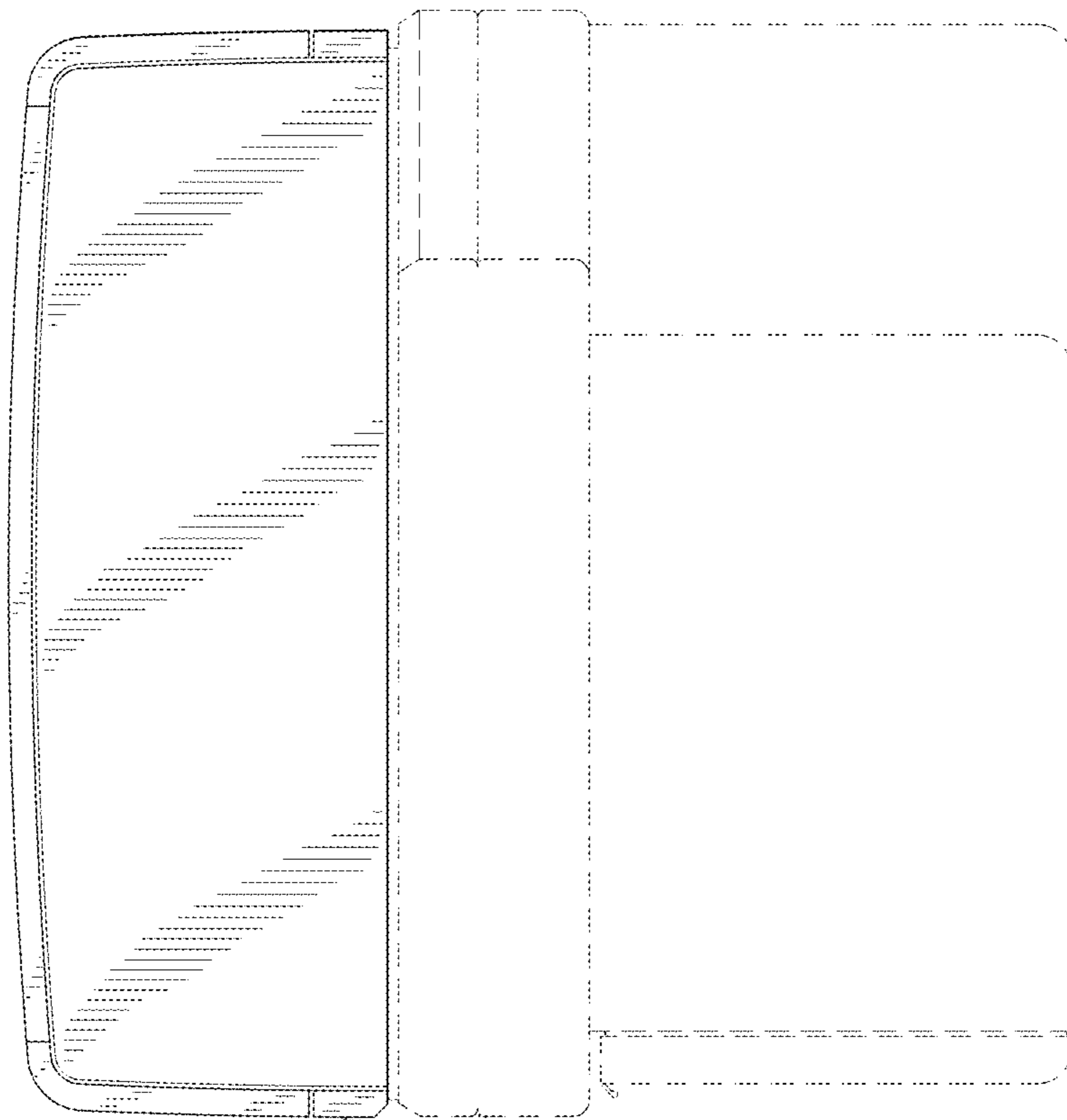


FIG. 6

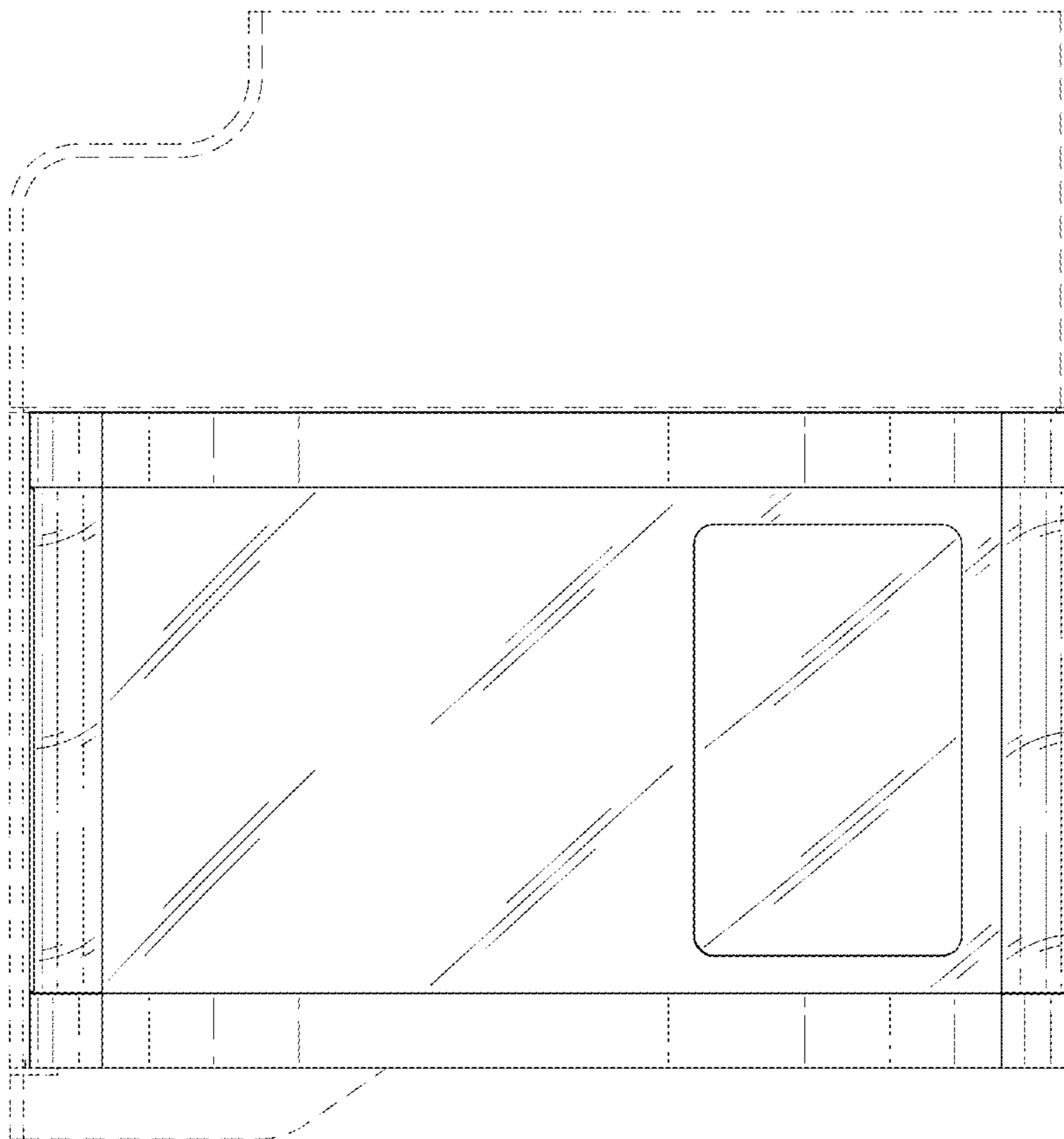


FIG. 7



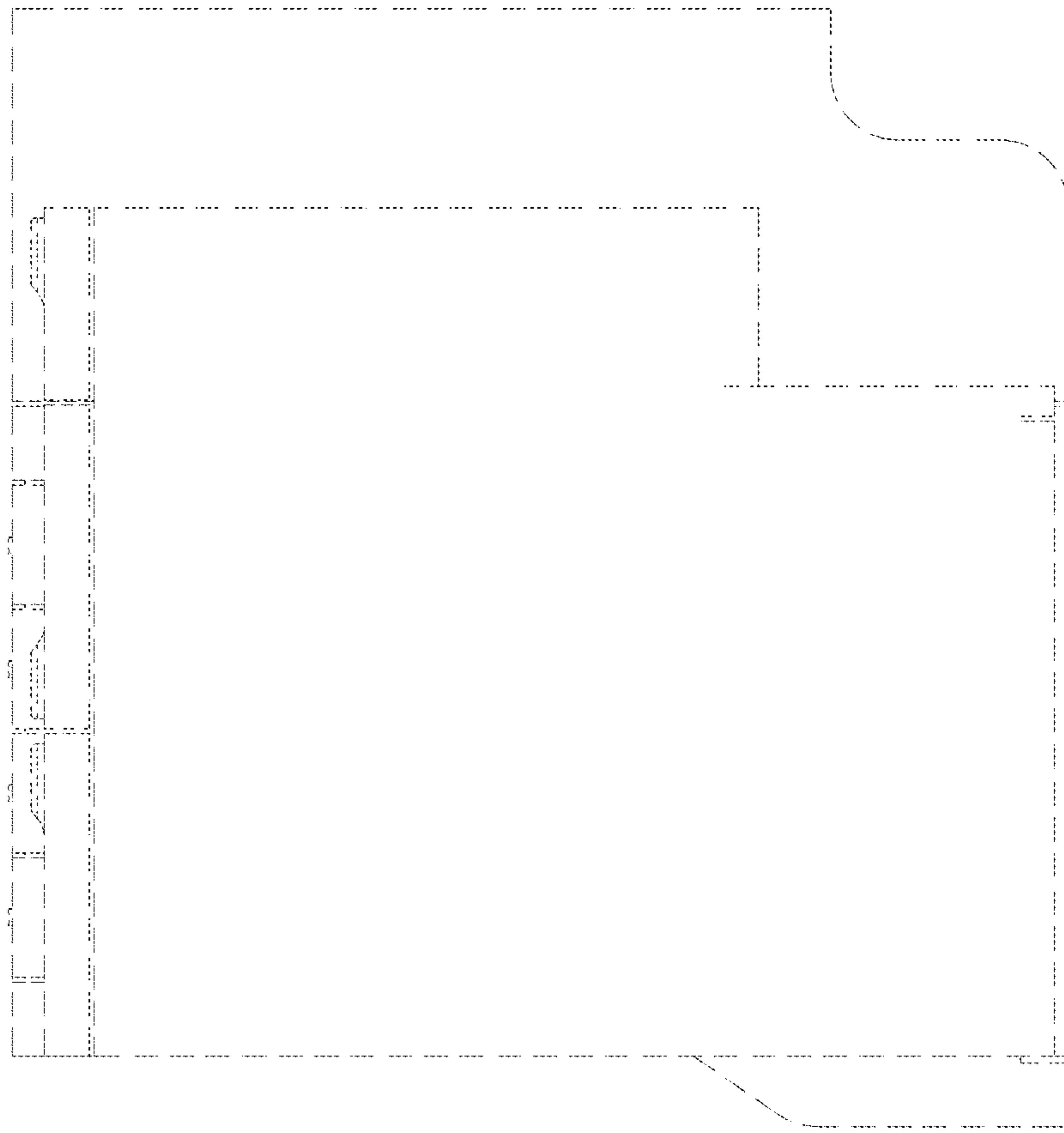


FIG. 8